



JAE Electronics, Inc.
June 6th, 2025

ENG-E25-075 - Distributors

PCN (Process Change Notice)

M120-55780

Additional Mold Dies &
New Production Location
To Keep Production Capacity

Part Number	Existing Mold Dies	Additional Mold Dies will be created	Completion of Add Mold Dies	Proposed PPAP Submission	Start of Mass Production (SOP)
M120-55780	Refer to the Below Item 1	Refer to the below Item 2	December 2025	February 2026	April 2026

1. Existing mold dies

- 620170-004 die w/ 8 cav: S, T, U, V, W, X, Y, Z
- 620170-005 die w/ 8 cav: A., B., C., D., E., F., G., H. (dot next to the letter)
- 620170-006 die w/ 8 cav: J., K., L., M., N., O., P., Q., R. (dot next to the letter)
- 620170-007 die w/ 8 cav: S., T., U., V., W., X., Y., Z., (dot next to the letter)
- 620170-008 die w/ 8 cav: A1, A2 ,A3, A4, A5, A6, A7, A8
- 620170-009 die w/ 8 cav: B1, B2, B3, B4, B5, B6,,B7, B8

2. New mold dies will be created

- 622491-001 die w/16 cav: 1A, 1B... to1R (excluding I & O)
- 622491-002 die w/ 16 cav: 2A, 2B... to ... 2R (excluding I & O)

3. Existing production location: Kaiwa
New production location: Yamaichi Seiko

➔ After approval, all mold dies will be produced at Yamaichi Seiko

Notes:

- PC = Process Change (Tooling: Transfer, Replacement, Refurbishment, or additional and Parts Produced at Additional Location, etc...)
- PPAP = Production Part Approval Process
 1. PC PPAP will only be prepared and provided to customer who already requested and received initial PPAP.
 2. If you request PC PPAP documents for this notification, please notify us ASAP.